

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Vivek Ramadoss</td> <td>08/25/2010</td> </tr> <tr> <td>Gopal C. Jha</td> <td>08/25/2010</td> </tr> <tr> <td>Christopher J. Healy</td> <td>08/25/2010</td> </tr> </tbody> </table>		Name	Execution Date	Vivek Ramadoss	08/25/2010	Gopal C. Jha	08/25/2010	Christopher J. Healy	08/25/2010				
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>QUALCOMM Incorporated</td> </tr> <tr> <td>Street Address:</td> <td>5775 Morehouse Drive</td> </tr> <tr> <td>Internal Address:</td> <td>Patent Department</td> </tr> <tr> <td>City:</td> <td>San Diego</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>92121-1714</td> </tr> </table>		Name:	QUALCOMM Incorporated	Street Address:	5775 Morehouse Drive	Internal Address:	Patent Department	City:	San Diego	State/Country:	CALIFORNIA	Postal Code:	92121-1714
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
<p>Fax Number: (858)658-2502</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 858-658-5787</p> <p>Email: Patent.Docketing.US@qualcomm.com</p> <p>Correspondent Name: QUALCOMM Incorporated</p> <p>Address Line 1: 5775 Morehouse Drive</p> <p>Address Line 2: Patent Department</p> <p>Address Line 4: San Diego, CALIFORNIA 92121-1714</p>													
NAME OF SUBMITTER:	Nicholas J. Pauley												
<p>Total Attachments: 2</p> <p>source=100661_ASG_09-14-2010#page1.tif</p> <p>source=100661_ASG_09-14-2010#page2.tif</p>													

CH \$40.00 12881549

PATENT

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REEL: 024984 FRAME: 0406

ASSIGNMENT

TO WHOM IT MAY CONCERN:

For the sum of One Dollar and other valuable consideration to us in hand paid, receipt of which is hereby acknowledged, be it known that We/I,

1. Vivek Ramadoss, a citizen of India, having a mailing address of 5775 Morehouse Drive, San Diego, CA 92121; and a resident of San Diego, California.
2. Gopal C. Jha, a citizen of India, having a mailing address of 5775 Morehouse Drive, San Diego, CA 92121; and a resident of San Diego, California.
3. Christopher J. Healy, a citizen of United States of America, having a mailing address of 5775 Morehouse Drive, San Diego, CA 92121; and a resident of San Diego, California.

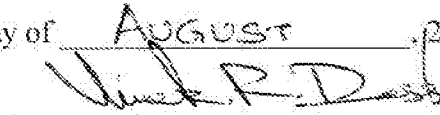
have sold, assigned and transferred and by these presents do sell, assign, transfer and set over unto QUALCOMM Incorporated, a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, its successors, legal representatives, or assigns, the entire right, title and interest in and to a certain invention relating to **Electronic Packaging with a Variable Thickness Mold Cap** by me devised and the application for United States Patent therefore filed in the United States Patent and Trademark Office on September 14, 2010, and assigned Serial No. 12/881,549, (and I hereby authorize and instruct **QUALCOMM Incorporated** to hereafter complete this Assignment by inserting the serial number and date in the space provided above when known), including, without limitation, all provisional patent applications, and all original and reissue patents granted thereof, and all divisions, continuations and continuations-in-part thereof, including the subject matter of any and all claims which may be obtained in every such patent, and all foreign rights to

ASSIGNMENT

said invention, and covenant that I have full right to do so, and agree that I will communicate to said corporation or its representatives all facts known to me respecting said invention, whenever requested, and testify in any legal proceedings, sign all lawful papers, make all rightful oaths and generally do everything possible to aid said corporation, its successors, assigns and nominees, to obtain and enforce proper patent protection for said invention in all countries.

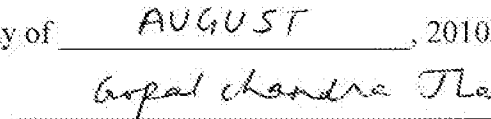
The Commissioner of Patents and Trademarks is requested to issue the Letters Patent which may be granted for said invention or any part thereof unto said corporation in keeping with this Assignment.

Done at San Diego, California this 25 day of AUGUST, 2010.



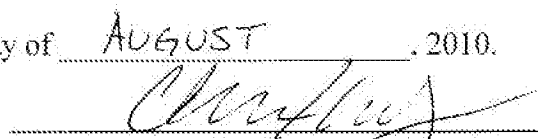
Vivek Ramadoss

Done at San Diego, California this 25 day of AUGUST, 2010.



Gopal C. Jha

Done at San Diego, California this 25 day of AUGUST, 2010.



Christopher J. Healy